



# P-Channel 20 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
- 20	$0.112$ at $V_{GS} = -4.5 \text{ V}$	- 3.1	3.3 nC		
- 20	0.142 at V <sub>GS</sub> = - 2.5 V	- 2.7	3.3 nC		

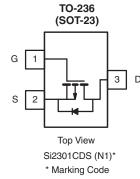
### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



### **APPLICATIONS**

· Load Switch



Ordering Information: Si2301CDS-T1-E3 (Lead (Pb)-free)

Si2301CDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $(T_A$	= 25 °C, unless otl	herwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 20	V		
Gate-Source Voltage	$V_{GS}$	± 8	ľ		
	T <sub>C</sub> = 25 °C		- 3.1		
Continuous Drain Current /T 150 °C)	T <sub>C</sub> = 70 °C		- 2.5	А	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 2.3 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		- 1.8 <sup>b, c</sup>		
Pulsed Drain Current	I <sub>DM</sub> - 10	- 10	1		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		- 1.3		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 0.72 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		1.6		
Maximum Daving Dissipation	T <sub>C</sub> = 70 °C	Б.	1.0	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	$P_{D}$	0.86 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		0.55 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	R <sub>thJA</sub>	120	145	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	62	78	G/VV	

### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 175  $^{\circ}\text{C/W}.$

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MOSFET SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•		•	
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250A		- 18		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.2		miv/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zava Cata Valta na Duain Course		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V	-		- 1	T .	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 6			Α	
Drain Course On State Decistores		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2.8 A		0.090	0.112		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 2.0 A		0.110	0.142	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 2.8 A		9.5		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			405		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		75			
Reverse Transfer Capacitance	C <sub>rss</sub>			55			
Total Cata Charge	$Q_g$	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 3 A		5.5	10		
Total Gate Charge		Q <sub>g</sub>		3.3	6	200	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -3 \text{ A}$		0.7		nC	
Gate-Drain Charge	Q <sub>gd</sub>			1.3			
Gate Resistance	$R_g$	f = 1 MHz		6.0		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			11	20		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_1 = 10 \Omega$		35	60	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		30	50		
Fall Time	t <sub>f</sub>			10	20	1	
Drain-Source Body Diode Characteristi	cs					•	
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 1.3		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 10	A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 0.7 A		- 0.8	- 1.2	٧	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			30	50	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 00 A 41/44 400 A / - T 05 00		25	50	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -3.0 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15		<b>n</b> -	
Reverse Recovery Rise Time	t <sub>b</sub>			15		ns	

#### Notes:

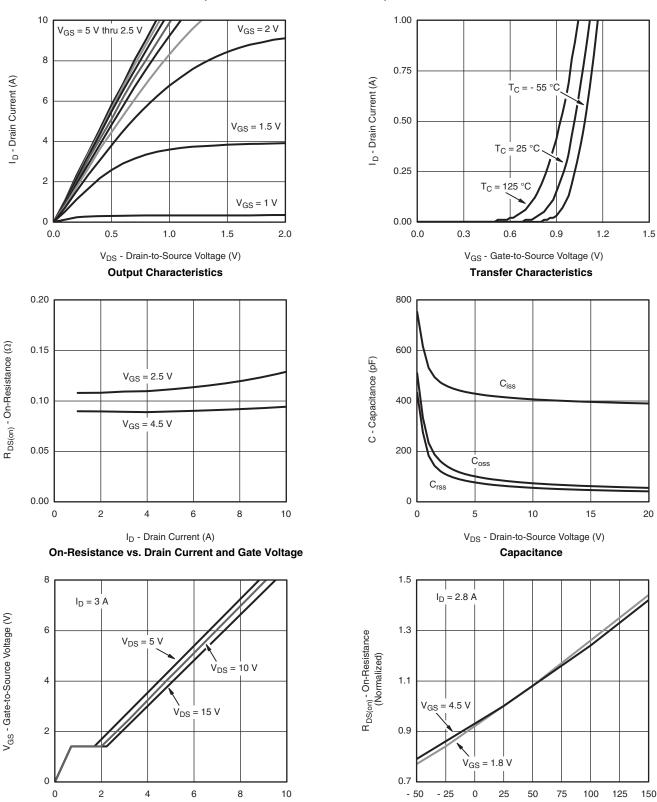
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Q<sub>q</sub> - Total Gate Charge (nC)

**Gate Charge** 

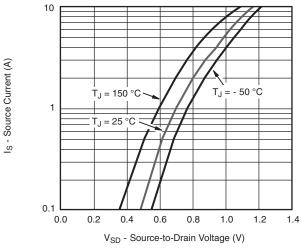
T<sub>J</sub> - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

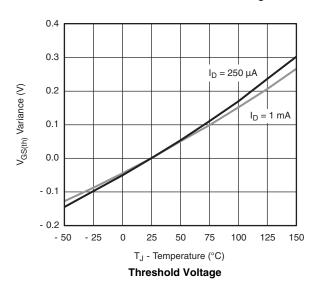
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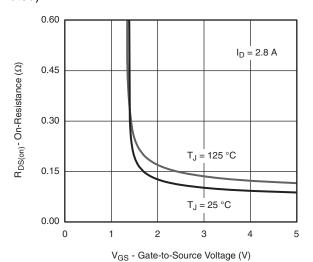
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# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

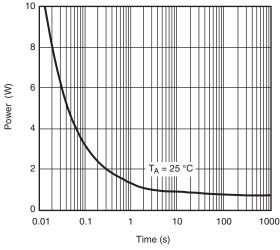


### Source-Drain Diode Forward Voltage

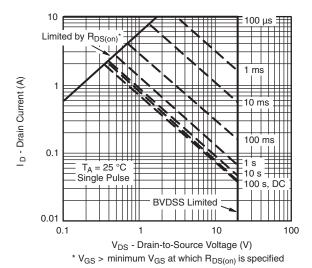




On-Resistance vs. Gate-to-Source Voltage

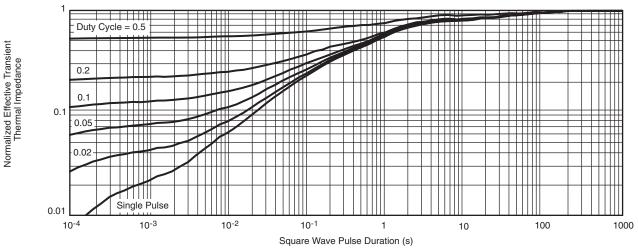


Single Pulse Power

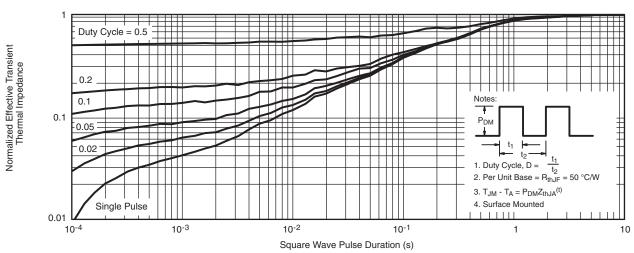




## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



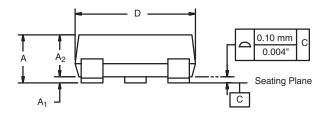
Normalized Thermal Transient Impedance, Junction-to-Foot

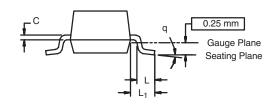
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# SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.037	4 Ref	
e <sub>1</sub>	1.90	BSC	0.074	.0748 Ref	
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64	Ref	0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
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### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE

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